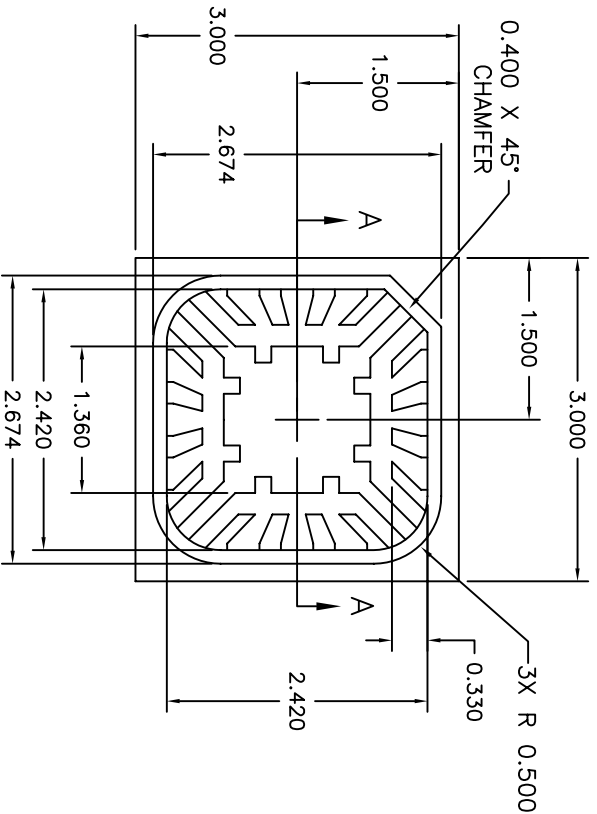


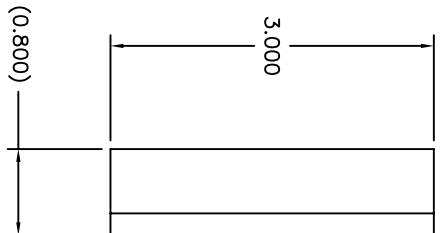
2

1

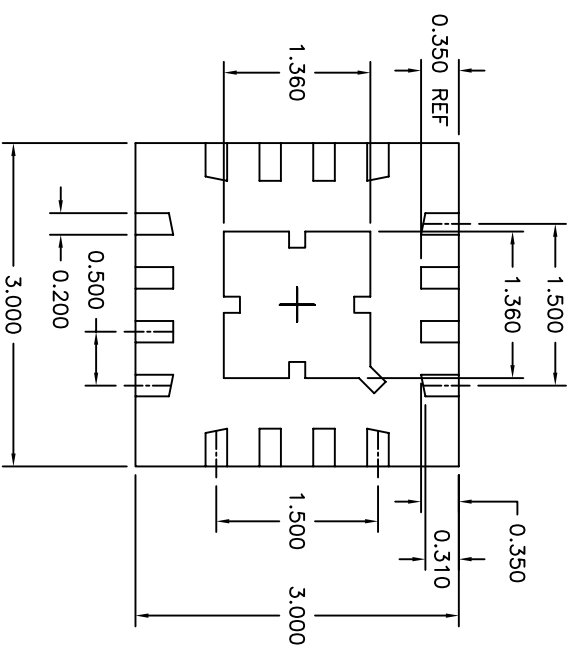
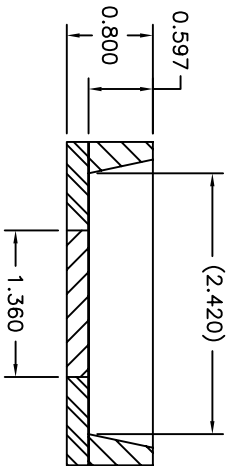
REVISIONS		APPROVED
ECN NO.	DATE	DESCRIPTION
10653	5/25/06	PRODUCTION RELEASE
		D.BENAVANDO



TOP VIEW



SECTION A-A



BOTTOM VIEW

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 1.360mm X 1.360mm.
 6. JEDEC OUTLINE: MO-220 (VEED)



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± .1°

DO NOT SCALE DRAWING

DRAWN BY	R. ALCORN	DATE	5/25/06
APP BY	P. FLASKERUD	DATE	5/25/06
CUSTOMER	---		

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SIZE	PART NO.	REV
A	MLP3X3-16-OP-01	1
SCALE	NONE	
CAD FILE	MLP3X3-16-OP-01-R1.DWG	SHEET 1 OF 1

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